



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

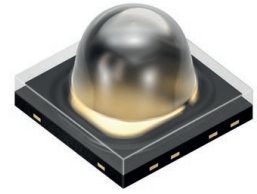
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



SFH 4718A

OSLON® Black

OSLON Black Series (850 nm) - 40°



Applications

- 3D Capturing
- Access Control (IRIS/Vein Scan, Face Recognition)
- CCTV Surveillance
- Gaming, Amusement, Gambling
- Safety and Security, CCTV
- VMS

Features:

- Package: diffuse silicone
- Corrosion Robustness Class: 3B
- ESD: 2 kV acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2)
- IR lightsource with high efficiency
- Low thermal resistance (Max. 16 K/W)
- Centroid wavelength 850 nm

Ordering Information

Type	Radiant intensity ¹⁾ $I_F = 1 \text{ A}; t_p = 10 \text{ ms}$ I_e	Radiant intensity ¹⁾ typ. $I_F = 1 \text{ A}; t_p = 10 \text{ ms}$ I_e	Ordering Code
SFH 4718A	400 ... 1000 mW/sr	730 mW/sr	Q65112A1520

Preliminary datasheet version

Maximum Ratings

$T_A = 25\text{ °C}$

Parameter	Symbol		Values
Operating temperature	T_{op}	min. max.	-40 °C 125 °C
Storage temperature	T_{stg}	min. max.	-40 °C 125 °C
Junction temperature	T_j	max.	145 °C
Reverse voltage ²⁾	V_R	max.	12 V
Forward current	I_F	max.	1000 mA
Surge current $D \leq 1$	I_{FSM}	max.	1 A
Power consumption	P_{tot}	max.	2.3 W
ESD withstand voltage acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2)	V_{ESD}	max.	2 kV

For the forward current and power consumption please see “maximum permissible forward current” diagram

Characteristics

$I_F = 1000 \text{ mA}$; $t_p = 10 \text{ ms}$; $T_A = 25 \text{ °C}$

Parameter	Symbol		Values
Peak wavelength	λ_{peak}	typ.	860 nm
Centroid wavelength	$\lambda_{\text{centroid}}$	typ.	850 nm
Spectral bandwidth at 50% $I_{\text{rel,max}}$	$\Delta\lambda$	typ.	34 nm
Half angle	φ	typ.	20 °
Dimensions of active chip area	L x W	typ.	0.75 x 0.75 mm x mm
Rise time (10% / 90%) $I_F = 1 \text{ A}$; $R_L = 50 \text{ } \Omega$	t_r	typ.	11 ns
Fall time (10% / 90%) $I_F = 1 \text{ A}$; $R_L = 50 \text{ } \Omega$	t_f	typ.	15 ns
Forward voltage	V_F	typ. max.	1.75 V 2.3 V
Reverse current ²⁾ $V_R = 5 \text{ V}$	I_R	max. typ.	10 μA 0.01 μA
Total radiant flux ³⁾ $I_F = 1 \text{ A}$; $t_p = 100 \text{ } \mu\text{s}$	Φ_e	typ.	665 mW
Temperature coefficient of brightness	TC_I	typ.	-0.3 % / K
Temperature coefficient of voltage	TC_V	typ.	-1 mV / K
Temperature coefficient of wavelength	TC_λ	typ.	0.3 nm / K
Thermal resistance junction solder point real ⁴⁾	R_{thJS}	max.	16 K / W

Brightness Groups

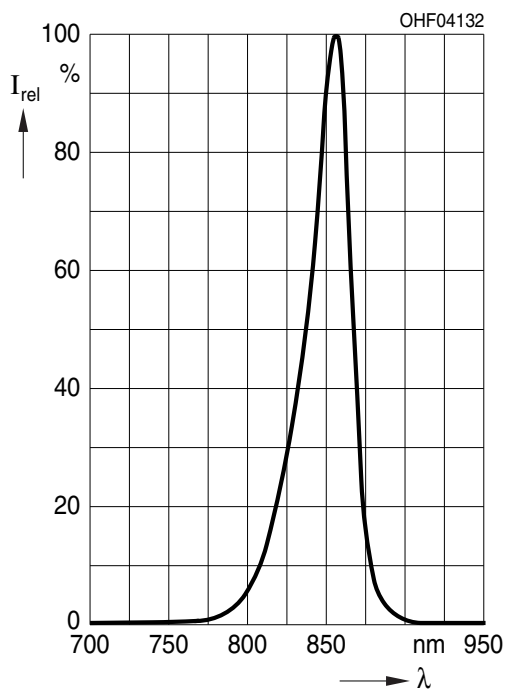
$T_A = 25 \text{ °C}$

Group	Radiant intensity $I_F = 1000 \text{ mA}$; $t_p = 10 \text{ ms}$ min. I_e	Radiant intensity $I_F = 1000 \text{ mA}$; $t_p = 10 \text{ ms}$ max. I_e
DA	400 mW/sr	630 mW/sr
DB	500 mW/sr	800 mW/sr
EA	630 mW/sr	1000 mW/sr

Only one group in one packing unit (variation lower 1.6:1).

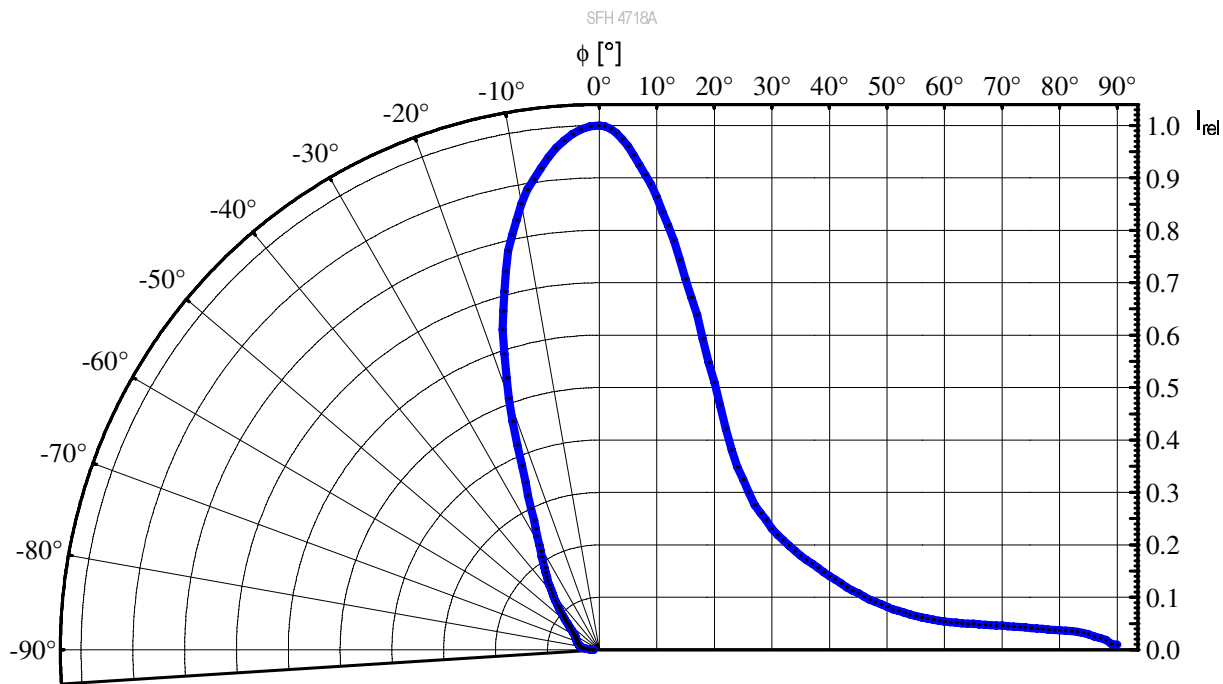
Relative Spectral Emission ^{5), 6)}

$I_{rel} = f(\lambda); I_F = 1000 \text{ mA}; t_p = 10 \text{ ms}$



Radiation Characteristics ^{5), 6)}

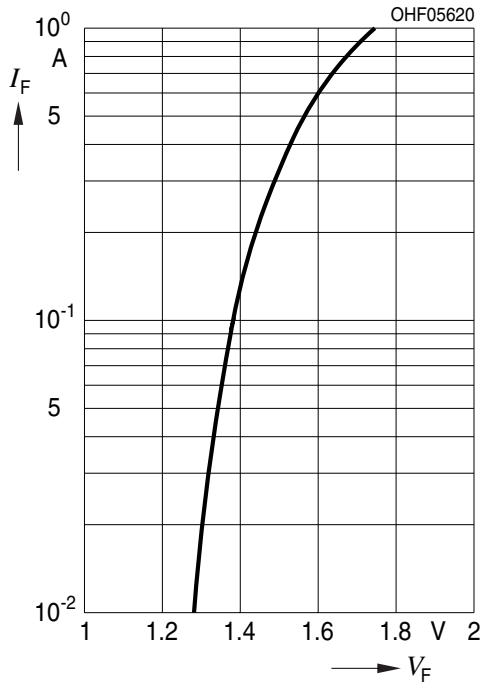
$I_{rel} = f(\phi)$



Preliminary datasheet version

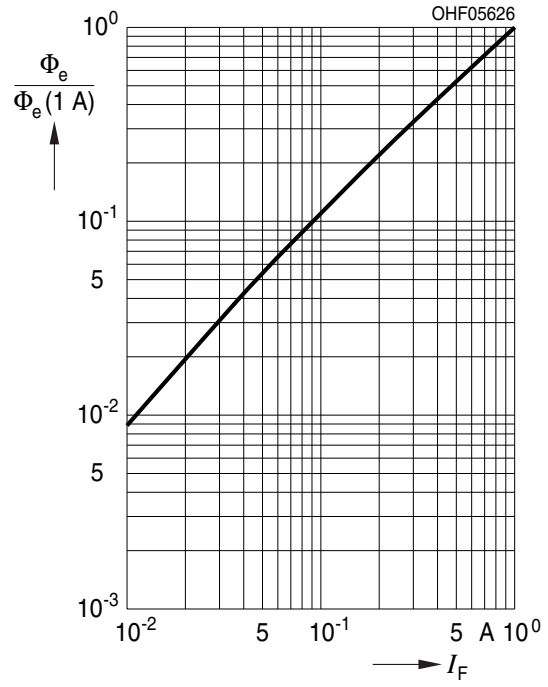
Forward current ^{5), 6)}

$I_F = f(V_F)$; single pulse; $t_p = 100 \mu s$



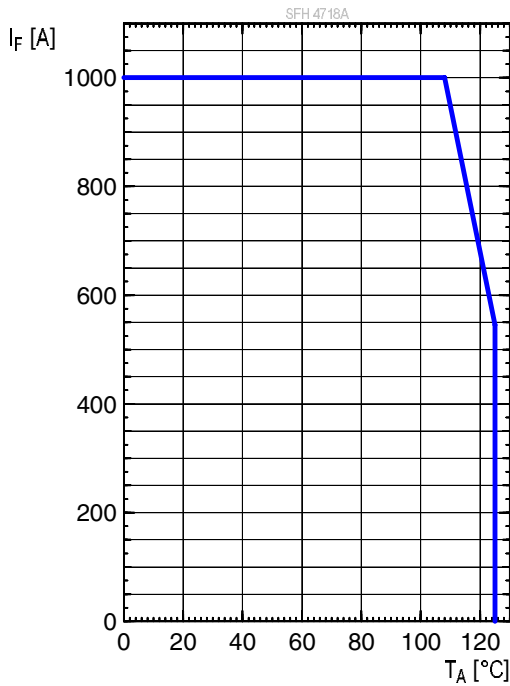
Relative Total Radiant Flux ^{5), 6)}

$\Phi_e / \Phi_e(1000mA) = f(I_F)$; single pulse; $t_p = 100 \mu s$



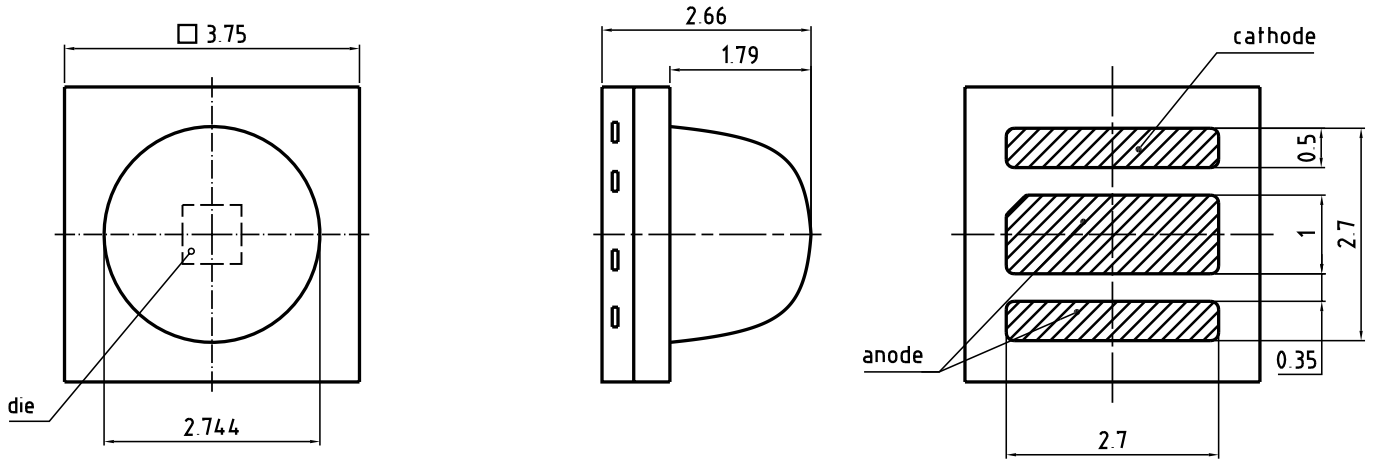
Max. Permissible Forward Current


$I_{F,max} = f(T_S)$; $R_{thJS} = 16 K / W$



Preliminary datasheet version

Dimensional Drawing ⁷⁾

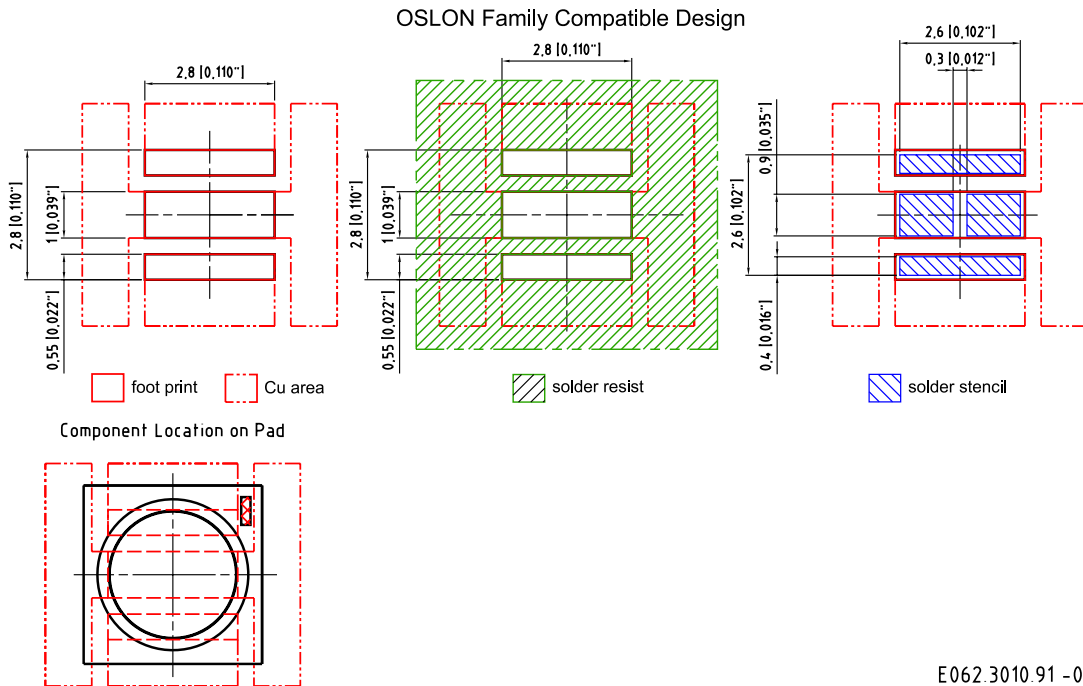


general tolerance ± 0.1
 lead finish Au 

C63062-A4 141-A15-02

Approximate Weight:	31.0 mg
Package marking:	Cathode
Corrosion test:	Class: 3B Test condition: 40°C / 90 % RH / 15 ppm H ₂ S / 14 days (stricter then IEC 60068-2-43)

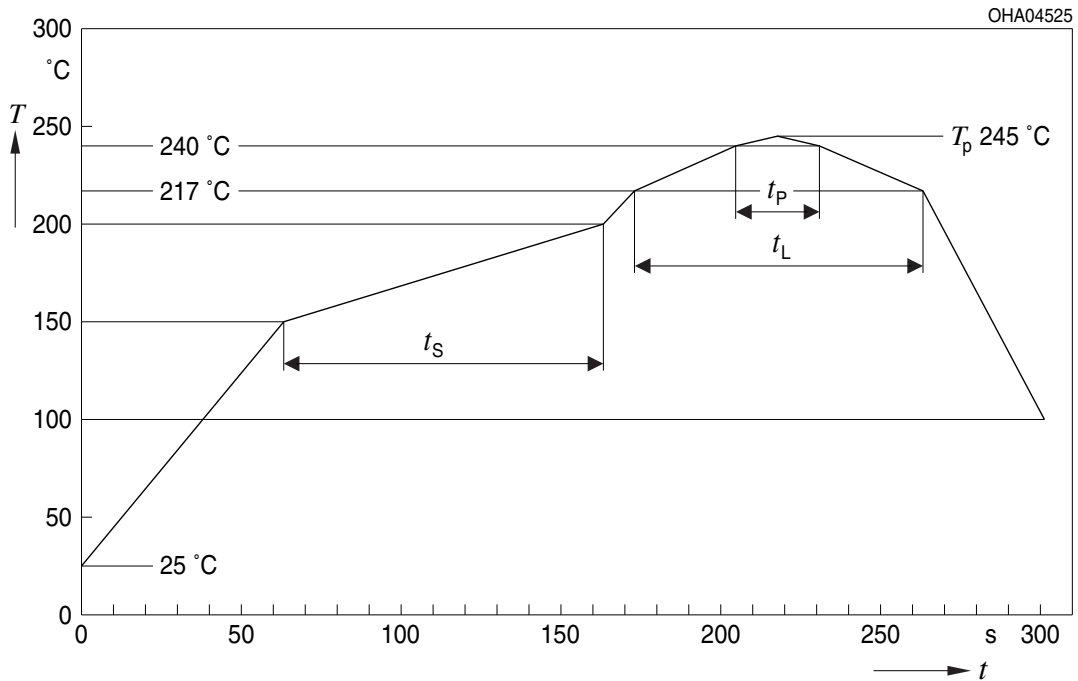
Recommended Solder Pad ⁷⁾



For superior solder joint connectivity results we recommend soldering under standard nitrogen atmosphere. Package not suitable for ultra sonic cleaning.

Reflow Soldering Profile

Product complies to MSL Level 2 acc. to JEDEC J-STD-020E

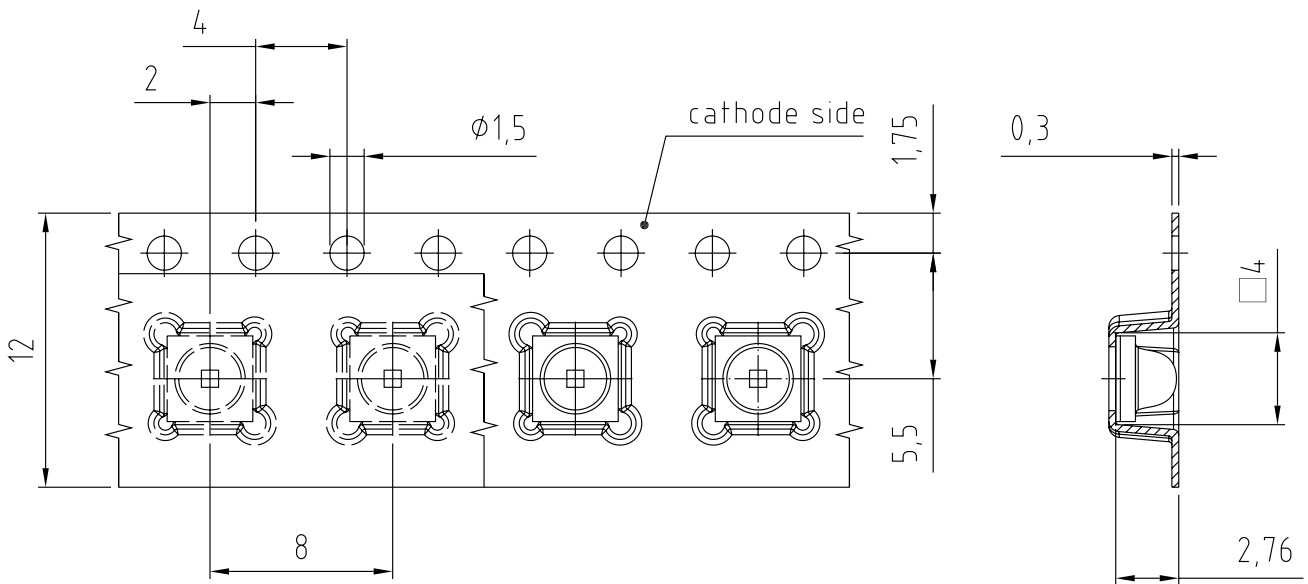


Preliminary datasheet version

Profile Feature	Symbol	Pb-Free (SnAgCu) Assembly			Unit
		Minimum	Recommendation	Maximum	
Ramp-up rate to preheat*) 25 °C to 150 °C			2	3	K/s
Time t_s T_{Smin} to T_{Smax}	t_s	60	100	120	s
Ramp-up rate to peak*) T_{Smax} to T_p			2	3	K/s
Liquidus temperature	T_L		217		°C
Time above liquidus temperature	t_L		80	100	s
Peak temperature	T_p		245	260	°C
Time within 5 °C of the specified peak temperature $T_p - 5$ K	t_p	10	20	30	s
Ramp-down rate* T_p to 100 °C			3	6	K/s
Time 25 °C to T_p				480	s

All temperatures refer to the center of the package, measured on the top of the component
 * slope calculation DT/Dt : Dt max. 5 s; fulfillment for the whole T-range

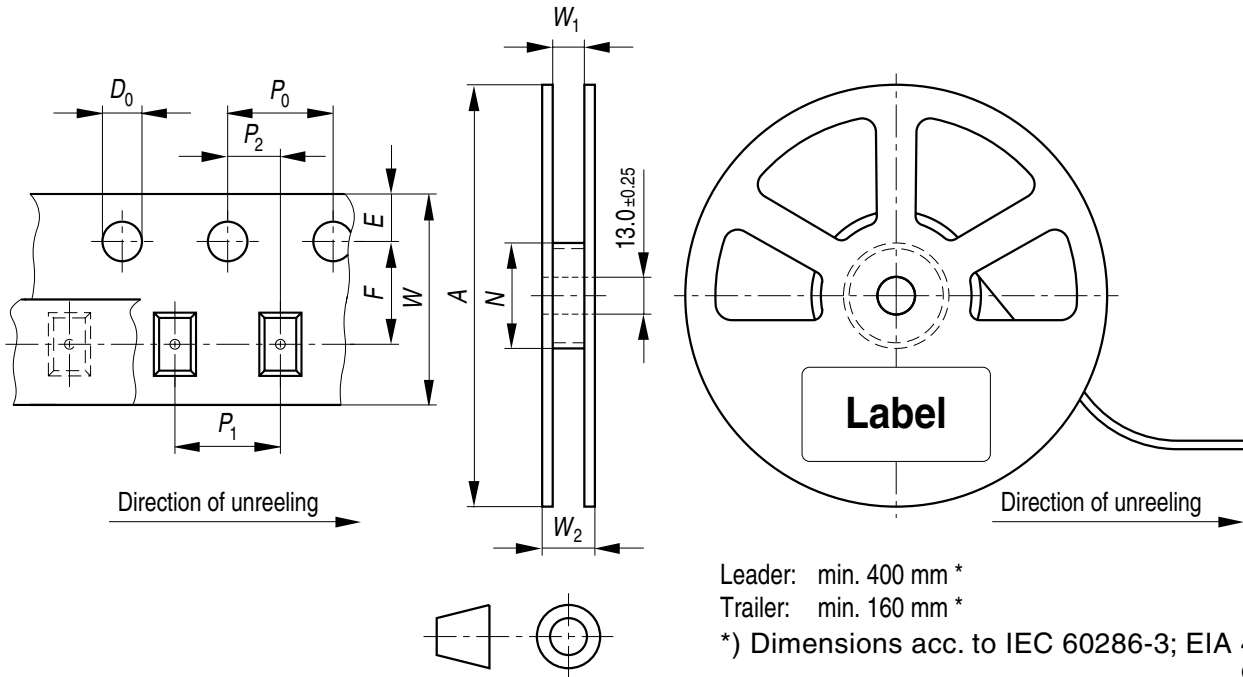
Taping ⁷⁾



Preliminary datasheet version

C63062-A4141-B15 -01

Tape and Reel ⁸⁾



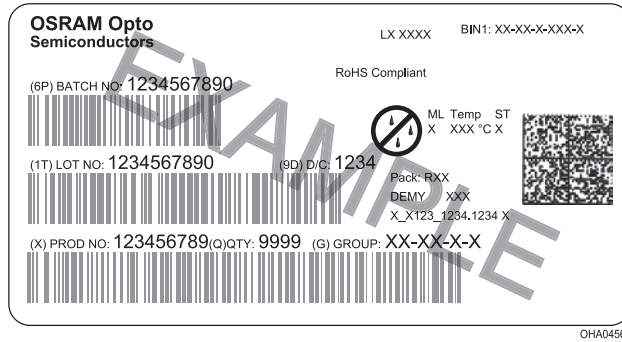
Leader: min. 400 mm *
 Trailer: min. 160 mm *

*) Dimensions acc. to IEC 60286-3; EIA 481-D
 OHAY0324

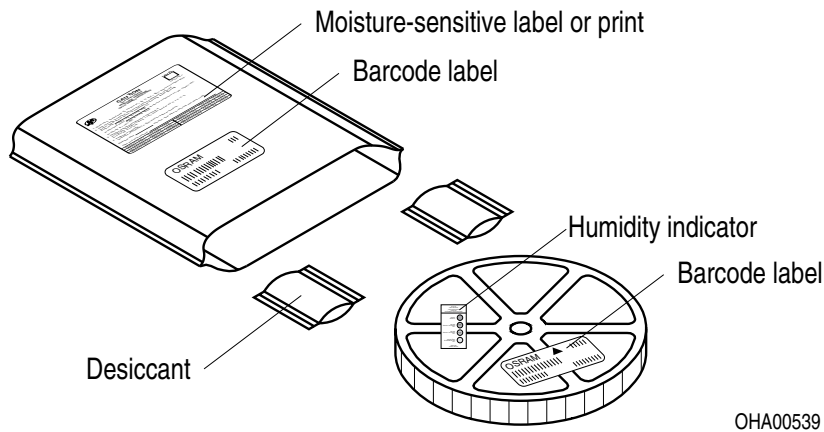
Reel dimensions [mm]

A	W	N _{min}	W ₁	W _{2max}	Pieces per PU
180 mm	12 + 0.3 / - 0.1	60	12.4 + 2	18.4	600

Barcode-Product-Label (BPL)

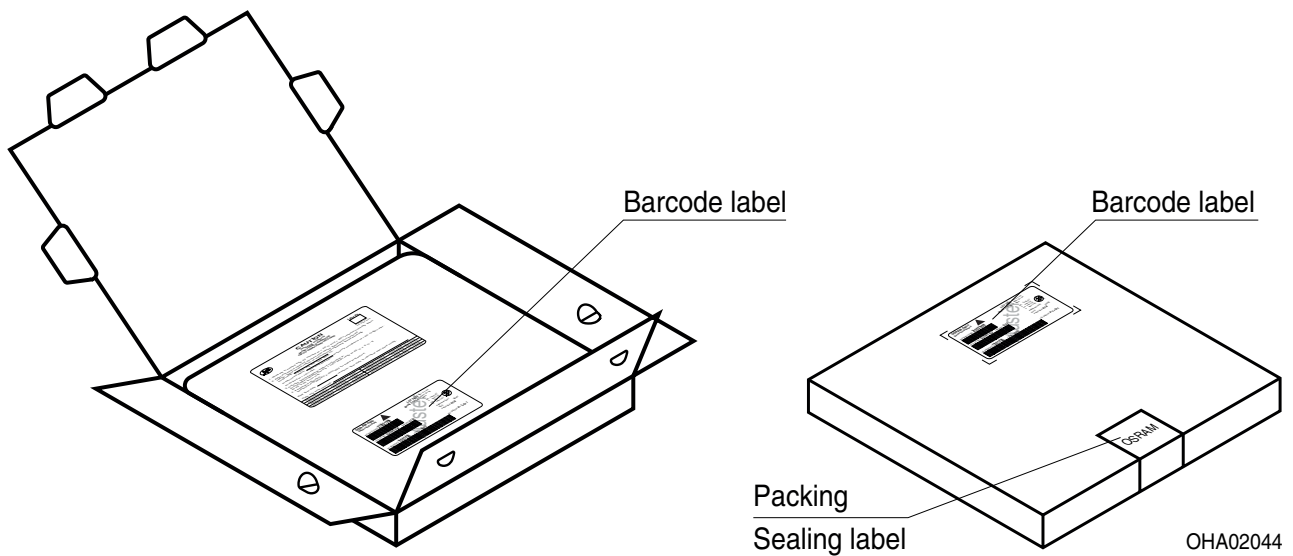


Dry Packing Process and Materials ⁷⁾



Moisture-sensitive product is packed in a dry bag containing desiccant and a humidity card according JEDEC-STD-033.

Transportation Packing and Materials ⁷⁾



Dimensions of transportation box in mm

Width	Length	Height
195 ± 5 mm	195 ± 5 mm	30 ± 5 mm

Notes

The evaluation of eye safety occurs according to the standard IEC 62471:2006 (photo biological safety of lamps and lamp systems). Within the risk grouping system of this IEC standard, the LED specified in this data sheet falls into the class **exempt group (exposure time 10000 s)**. Under real circumstances (for exposure time, conditions of the eye pupils, observation distance), it is assumed that no endangerment to the eye exists from these devices. As a matter of principle, however, it should be mentioned that intense light sources have a high secondary exposure potential due to their blinding effect. When looking at bright light sources (e.g. headlights), temporary reduction in visual acuity and afterimages can occur, leading to irritation, annoyance, visual impairment, and even accidents, depending on the situation.

Subcomponents of this LED contain, in addition to other substances, metal filled materials including silver. Metal filled materials can be affected by environments that contain traces of aggressive substances. Therefore, we recommend that customers minimize LED exposure to aggressive substances during storage, production, and use. LEDs that showed visible discoloration when tested using the described tests above did show no performance deviations within failure limits during the stated test duration. Respective failure limits are described in the IEC60810.

For further application related informations please visit www.osram-os.com/appnotes

Disclaimer

OSRAM OS assumes no liability whatsoever for any use of this document or its content by recipient including, but not limited to, for any design in activities based on this preliminary draft version. OSRAM OS may e.g. decide at its sole discretion to stop developing and/or finalising the underlying design at any time.

Disclaimer

Language english will prevail in case of any discrepancies or deviations between the two language wordings.

Attention please!

The information describes the type of component and shall not be considered as assured characteristics. Terms of delivery and rights to change design reserved. Due to technical requirements components may contain dangerous substances.

For information on the types in question please contact our Sales Organization.

If printed or downloaded, please find the latest version in the OSRAM OS Website.

Packing

Please use the recycling operators known to you. We can also help you – get in touch with your nearest sales office.

By agreement we will take packing material back, if it is sorted. You must bear the costs of transport. For packing material that is returned to us unsorted or which we are not obliged to accept, we shall have to invoice you for any costs incurred.

Product safety devices/applications or medical devices/applications

OSRAM OS components are not developed, constructed or tested for the application as safety relevant component or for the application in medical devices.

In case Buyer – or Customer supplied by Buyer– considers using OSRAM OS components in product safety devices/applications or medical devices/applications, Buyer and/or Customer has to inform the local sales partner of OSRAM OS immediately and OSRAM OS and Buyer and /or Customer will analyze and coordinate the customer-specific request between OSRAM OS and Buyer and/or Customer.

Glossary

- 1) **Radiant intensity:** Measured at a solid angle of $\Omega = 0.01$ sr
- 2) **Reverse Operation:** Reverse Operation of 10 hours is permissible in total. Continuous reverse operation is not allowed.
- 3) **Total radiant flux:** Measured with integrating sphere.
- 4) **Thermal resistance:** junction - soldering point, of the device only, mounted on an ideal heatsink (e.g. metal block)
- 5) **Typical Values:** Due to the special conditions of the manufacturing processes of LED, the typical data or calculated correlations of technical parameters can only reflect statistical figures. These do not necessarily correspond to the actual parameters of each single product, which could differ from the typical data and calculated correlations or the typical characteristic line. If requested, e.g. because of technical improvements, these typ. data will be changed without any further notice.
- 6) **Testing temperature:** $T_A = 25^\circ\text{C}$
- 7) **Tolerance of Measure:** Unless otherwise noted in drawing, tolerances are specified with ± 0.1 and dimensions are specified in mm.
- 8) **Tape and Reel:** All dimensions and tolerances are specified acc. IEC 60286-3 and specified in mm.

Published by OSRAM Opto Semiconductors GmbH
Leibnizstraße 4, D-93055 Regensburg
www.osram-os.com © All Rights Reserved.

EU RoHS and China RoHS compliant product



此产品符合欧盟 RoHS 指令的要求；
按照中国的相关法规和标准，不含有毒有害物质或元素。